

SOT1712-1

BGA388, plastic ball grid array package; 388 balls; 1 mm pitch; 27 mm x 27 mm x 1.95 mm body

7 January 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA388
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	MS-034 AAL-1
Mounting method type	S (surface mount)
Issue date	04-03-2016
Manufacturer package code	98ARS23880W

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	27	-	mm
package width	-	27	-	mm
package height	-	1.95	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	388	-	



2 Package outline

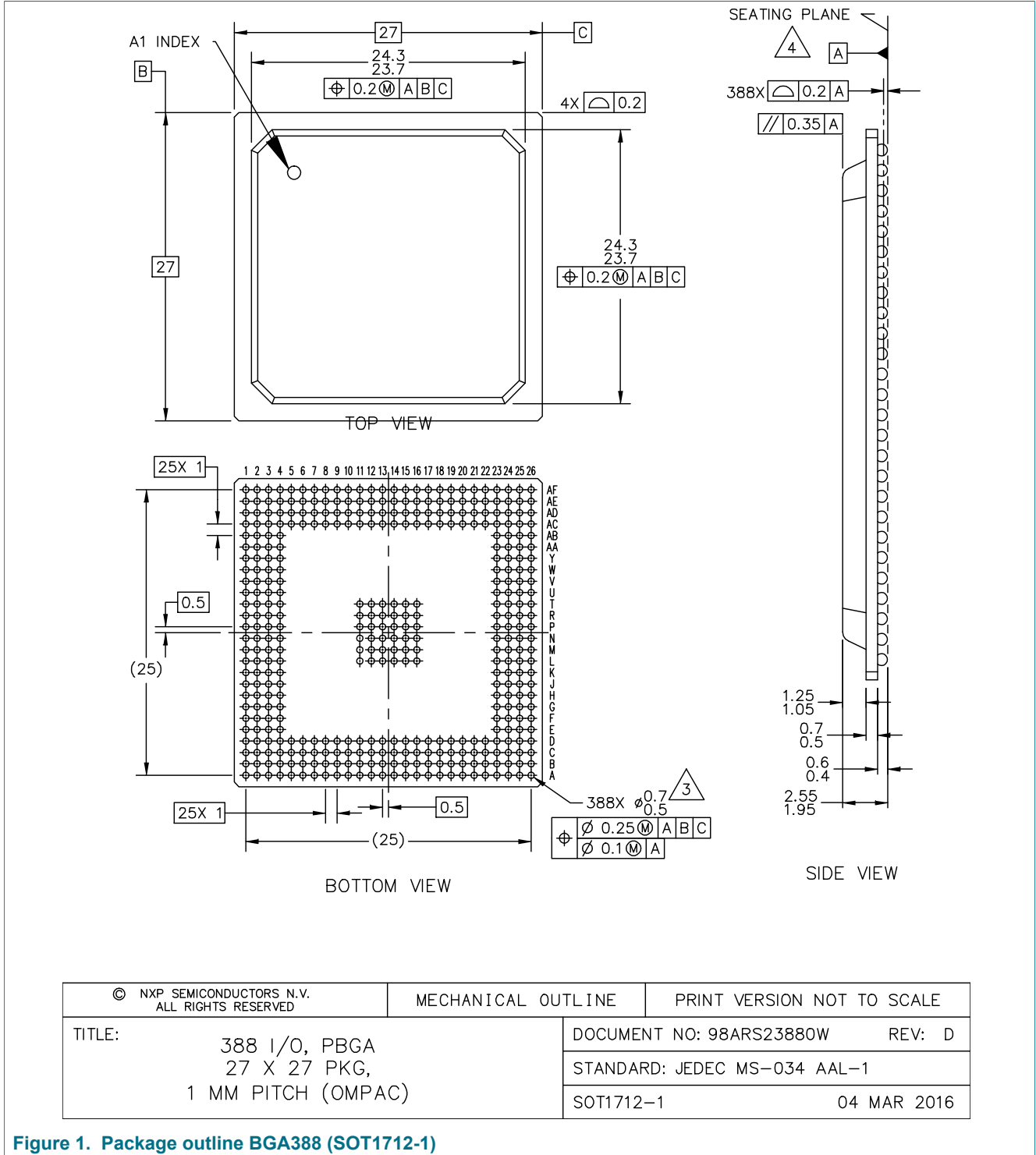



Figure 1. Package outline BGA388 (SOT1712-1)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4.  DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PACKAGE CODES:
 5254 - 2 LAYER SUBSTRATE PACKAGE
 5367 - 4 LAYER SUBSTRATE PACKAGE

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TITLE: 388 I/O, PBGA 27 X 27 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ARS23880W	REV: D
	STANDARD: JEDEC MS-034 AAL-1	
	SOT1712-1	04 MAR 2016

Figure 2. Package outline note BGA388 (SOT1712-1)

3 Legal information

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